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Intel® Ethernet Controller X550-AT2

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Specifications

Essentials	
Status	Launched
Launch Date	Q4'15
Expected Discontinuance	2023
Lithography	28 nm
TDP	11 W
Recommended Customer Price	
Datasheet	Link
Description	Fully integrated 10GBASE-T controller designed for LAN-on-Motherboard (LOM) & Converged Network Adapters (CNA)
Product Brief	Link
Supported Operating Systems	FreeBSD 10.2, Linux RHEL 6.7, Linux RHEL 7.1, Linux SLES 11 SP4, Linux SLES 11 SP4-IA64, Linux SLES 12, Linux Stable Kernel version 2.6/3.x, Linux Stable Kernel version 4.x, UEFI 2.1, UEFI 2.3, UEFI 2.4, VMware ESXi 5.5/6.0, Windows 7 SP1, Windows 8, Windows 8.1, Windows 10, Windows Server 2008 R2, Windows Server 2008 R2 Core, Windows Server 2008 R2 Hyper-V, Windows Server 2012, Windows Server 2012 Core, Windows Server 2012 Hyper-V, Windows Server 2012 R2, Windows Server 2012 R2 Core, Windows Server 2012 R2 Hyper-V, WinPE 3.0 (2008 R2 PE), WinPE 4.0 (2012 PE), WinPE 5.0 (2012 R2 PE)
Operating Temperature Range	0°C to 55°C
Conflict Free	Yes

Networking Specifications

# of Ports	Dual
Data Rate Per Port	10/5.0/2.5/1 GbE (NBASE-T in Linux Only)
System Interface Type	PCIe v3.0 (8.0GT/s)
NC Sideband Interface	Yes
Jumbo Frames Supported	Yes
Controller	ELX550AT2
100Base-T	Yes
1000Base-T	Yes
10GBase-T	Yes

Package Specifications

Package Size	17mm x 17mm
Low Halogen Options Available	See MDDS

Related Products

- [Intel® 10 Gigabit Ethernet Network Connection](#)
- [Intel® Ethernet Controller X550 Series](#)
- [Products formerly Sageville](#)



[Learn how Intel is pursuing conflict-free technology. >](#)

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PCN/MDDS Information

SLL2F
943743: [PCN](#) | [MDDS](#)
SLL2E
943736: [PCN](#) | [MDDS](#)

Intel® Virtualization Technology for Connectivity

Flexible Port Partitioning	Yes
Virtual Machine Device Queues (VMDq)	Yes
PCI-SIG* SR-IOV Capable	Yes

Advanced Technologies

Intel® Virtualization Technology for Connectivity (VT-c)	VMDq, SR-IOV
Fiber Channel over Ethernet	Yes
MACsec IEEE 802.1 AE	No
IEEE 1588	Yes
Supported Under vPro	No
iWARP/RDMA	No
Intel® Ethernet Power Management	Yes
Intel® Data Direct I/O Technology	Yes
Intelligent Offloads	Yes
Storage Over Ethernet	iSCSI, FCoE, NFS

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rule to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

The Recommended Customer -unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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